



Attorney's Docket No.: 07402-039001

*SA Chuva*  
7-25-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Carlson, et al. Art Unit : 2815  
Serial No.: 09/547,061 Examiner : Lourdes Cruz  
Filed : April 7, 2000  
Title : INSULATOR/METAL BONDING ISLAND FOR ACTIVE AREA  
SILVER EPOXY BONDING

Commissioner for Patents  
Washington, D.C. 20231

RESPONSE

In response to the action mailed March 15, 2001, please  
amend the application as follows:

In the claims:

\ Please amend claims 1, 9, and 13 as follows:

-- 1. (Amended) A semiconductor interconnection system,  
comprising:

a semiconductor die;

first and second conductive contacts, said first  
conductive contact coupled to a surface of said semiconductor  
die, and said second conductive contact coupled to an external  
structure;

a silver epoxy bond interposed between said first and  
second conductive contacts, said epoxy bond providing electrical

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